



SOD70

plastic near cylindrical single-ended package; 2 in-line leads

8 February 2016

Package information

1. Package summary

Terminal position code	S (single)
Package type descriptive code	PBCYT2
Package type industry code	PBCYT2
Package style descriptive code	PBCYT (plastic bottom (leads) cylindrical; through-hole)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	T (through-hole mount)
Issue date	15-9-2006

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.4	-	4.6	4.8	mm
E	package width	3.6	-	3.9	4.2	mm
A ₂	package height	5	-	5.1	5.2	mm
n ₂	actual quantity of termination	-	-	2	-	



2. Package outline

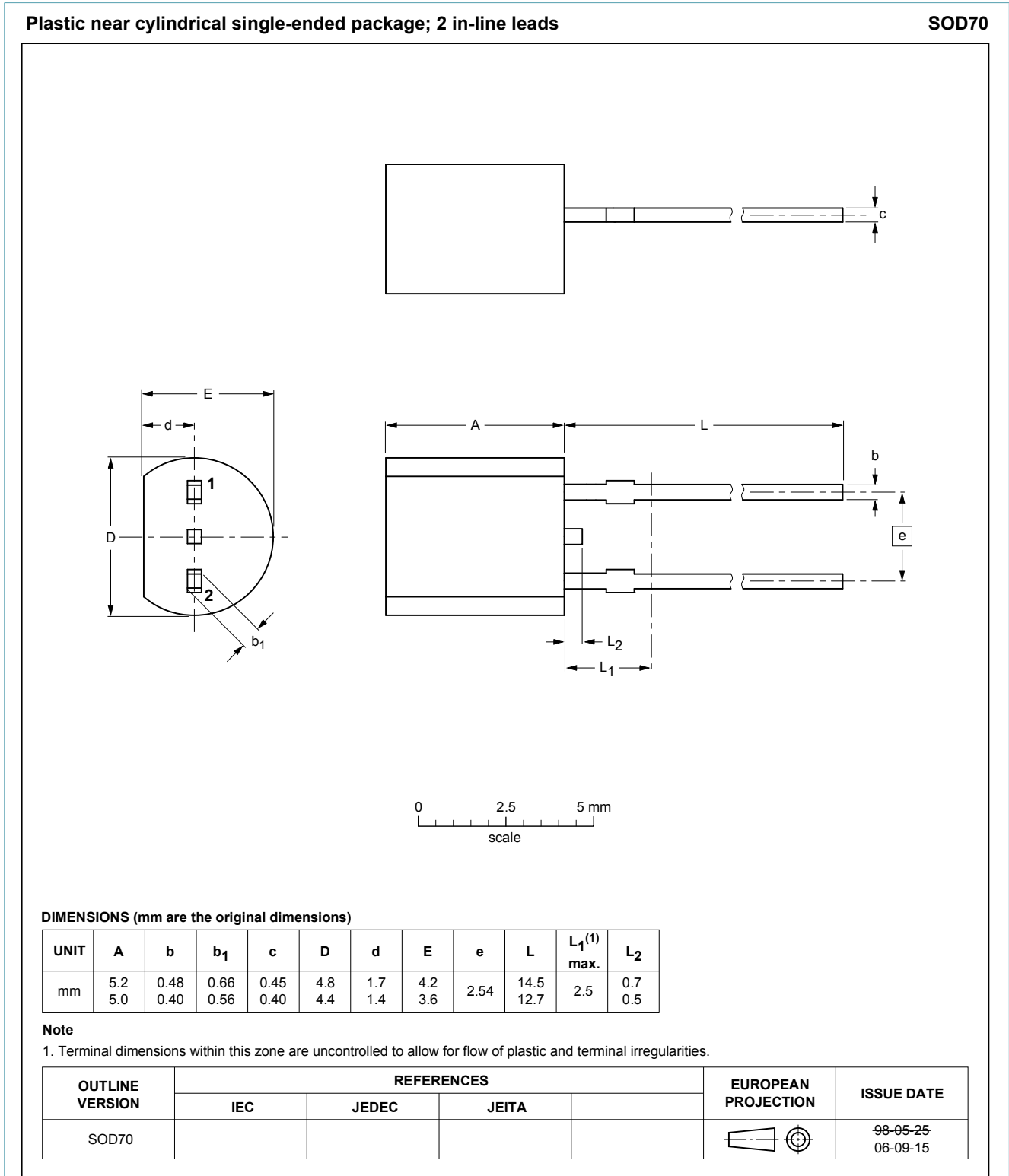


Fig. 1. Package outline PBCYT2 (SOD70)

3. Legal information

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